



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D

*\* : Required Field*

Supplier Information			
<b>Company Name *</b>	<b>STMicroelectronics</b>	<b>Response Date *</b>	2017-05-10
<b>Contact Name *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Authorized Representative *</b>	Rossana Bonaccorso	<b>Representative Title</b>	ADG MD Champion
<b>Representative Phone *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**


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Legal Statement			
<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard

**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STD80N6F7	6MDP*OD6CTC2	A	3068	2017-05-10
	Amount	UoM	Unit type	ST ECOPACK Grade
	330.00	mg	Each	ECOPACK2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NA	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SIP	6.5-6.1-2.3	3	GULL WING	
Comment	TO 252 DPAK			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

Query : California Prop65 list, dated 27th January 2017			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.02	die backside metal	61
Lead	2.63	soft solder	7970
Cobalt	0.46	leadframe alloy	1397

QueryList : REACH-12th January 2017				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	6MDP*0D6CTC2					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	0.843	mg	supplier	die	Silicon (Si)	7440-21-3		0.742	mg	880190	2248
				supplier	metallization	Aluminium (Al)	7429-90-5		0.049	mg	58126	148
				supplier	metallization	Silver (Ag)	7440-22-4		0.007	mg	8304	21
				supplier	metallization	Titanium (Ti)	7440-32-6		0.005	mg	5930	15
				supplier	Passivation	Silicon Oxide	7631-86-9		0.012	mg	14235	36
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.001	mg	1186	3
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.020	mg	23725	61
				supplier	back side metallization	Silver (Ag)	7440-22-4		0.007	mg	8304	21
Leadframe	Copper & its alloys	164.628	mg	supplier	alloy	Copper (Cu)	7440-50-8		163.838	mg	995201	496479
				supplier	alloy	CopperPhosphorous (CuP)	12517-41-8		0.329	mg	1999	997
				supplier	alloy	Cobalt (Co)	7440-48-4		0.461	mg	2800	1397
Soft solder	Solder	2.754	mg	JIG - R	solder	Lead (Pb)	7439-92-1	7a-Lead in high mel	2.630	mg	954975	7970
				supplier	solder	Silver (Ag)	7440-22-4		0.069	mg	25054	209
				supplier	solder	Tin (Sn)	7440-31-5		0.055	mg	19971	168
Bonding wires	Other inorganic materials	0.147	mg	supplier	wire	Copper (Cu)	7440-50-8		0.058	mg	75423	176
				supplier	wire	Aluminium (Al)	7429-90-5		0.711	mg	924577	2155
Encapsulation	Other Organic Materials	159.961	mg	supplier	mold compound	Silica, vitreous	60676-86-0		139.966	mg	875001	424139
				supplier	mold compound	Tetramethyl-biphenyl-diyl-bis oxymethylene-bi	EC 413-900-7		6.398	mg	39997	19388
				supplier	mold compound	Epoxy Resin	25068-38-6		4.799	mg	30001	14542
				supplier	mold compound	phenol resin	29690-82-2		7.998	mg	50000	24236
				supplier	mold compound	Carbon black	1333-86-4		0.800	mg	5001	2424
Connections coating	Solder	1.045	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		1.045	mg	1000000	3167